



ISO 9001



BF322513 Series

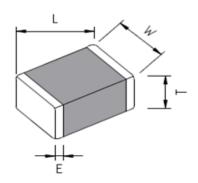
Features:

- These small size chips generate high impedance.
- Excellent solderability and high heat resistance for either flow or reflow soldering.
- Monolithic structure for high reliability.
- Low DC resistance structure of electrode prevents wasteful electric power consumption.
- Operating temperature range of -55°C to +125°C
- Storage temperature range of -10°C to +40°C

Applications:

- Circuit where a stable ground is unavailable.
- Various automotive electronics, various electronic equipment, digital communication equipment.
- Mother board, tablet PC, laptop, desktop computer and peripheral equipment.
- Mobile phone, smart phone, PND.

Shapes And Dimensions: (Unit:mm)



L	w	Т	E
3.2 ± 0.20	2.5 ± 0.20	1.3 ± 0.20	0.6~1.0

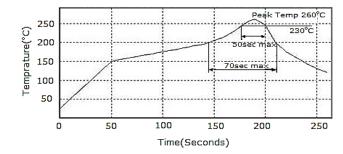
Part Number Code:

BF 322513 A 121 -E ① ② ③ ④ ⑤

- 1: Series
- 2: Dimensions LxWxT
- 3: Material Code
- 4: Normal Impedance
- 5 : Lead-Free

Reflow Profile:

Peak Temp: 260°C Max time above 230°C 50sec Max time above 200°C 70sec



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Part No.	Impedance Ω±25% @100MHz	DCR(Ω) (max.)	Rated Current (mA) (max.)
BF322513A310	31	0.10	500
BF322513A520	52	0.30	400
BF322513A600	60	0.30	400
BF322513B310	31	0.10	500

